

## THT soldering technology

The term "soldering" is defined in DIN 8505:

"Soldering is a method of connecting metallic materials using an additional melting metal, if necessary with the assistance of a flux and/or protective gas. The melting temperature of the solder must lie beneath the minimum melting temperature of the base metals being connected. These base metals shall be tinned without melting themselves."

Soft solders commonly used on electronic equipment are to DIN 1707-100. Today's lead free solders have a melting range between 217 °C and 227 °C depending on the composition of the alloy. For soldering metallic materials the flux is defined in DIN EN 29 454-1. Tests are explained in DIN 8526. For soldering male connectors into printed circuit boards, see recommendations for soldering on page 00.06.

## SMC soldering technology

The continuing trend towards miniaturisation has revolutionised the assembly of electronic components. For the past 15 years, most components have been secured directly to the pcb surface by means of Surface Mount Technology (SMT). By dispensing with drilled holes on the pcb, a space saving of up to 70 percent is achieved.

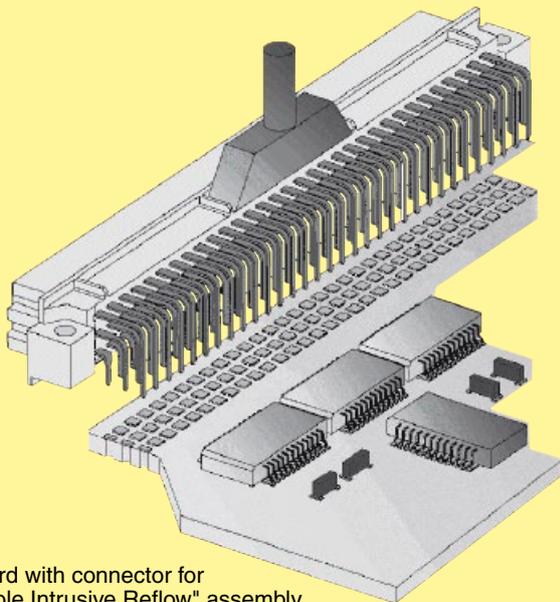


Fig. 1: SMT board with connector for "Pin in Hole Intrusive Reflow" assembly

Today, typical components such as resistors, ICs, capacitors, and connectors with straight terminal pins are almost exclusively fitted using SMD (Surface Mount Device) technology in mass production. In contrast, angled SMD connectors at the edge of the board have not been successful because of tolerance problems (co-planarity) and stresses during mating. Modified solder connectors for assembly with "Pin in Hole Intrusive Reflow" process offer a better solution. These can be mounted at low cost, utilising existing SMD production lines.

### "Pin in Hole Intrusive Reflow"

In this process, the connector is inserted into plated through holes in a comparable way to conventional component mounting. All other components can be assembled on the pcb surface.

The components are positioned using pick-and-place machines. These automatic assembly machines differ according to whether the components are small, lightweight or bulky. Connectors are considered bulky (odd form) because of their comparatively heavy weight and large volume which makes them more difficult to grip. Furthermore, machines for odd form components must have higher insertion power to fit the components into pcb holes, which are filled with solder paste. As a rule, modern SMC production lines are equipped with both types of machine, therefore the "Pin in Hole Intrusive Reflow" process generally entails no extra investment costs for the user.

### Conventional assembly process:

1. Application of solder paste
2. Positioning the components
3. Positioning odd form components
4. Reflow soldering
5. Pressing in or partially dip soldering the connector at the board edge
6. Quality inspection

### "Pin in Hole Intrusive Reflow" assembly:

1. Application of solder paste
2. Positioning the components
3. Positioning odd form components
4. Reflow soldering
5. Pressing in or partially dip soldering the connector at the board edge
6. Quality inspection

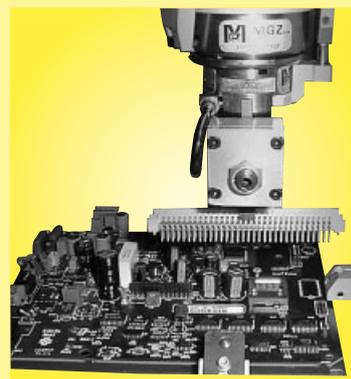


Fig. 2: Pick-and-place machine for odd form components (Courtesy of JOT Automation GmbH)